



1374.20289RC6

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. MAEJIMA, et al.

Serial No: 09/704,529

Filed: November 3, 2000

Title: WAFER HAVING CHAMFERED BEND PORTIONS IN THE  
JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER  
AND THE CUT-AWAY PORTION OF THE WAFER

Group: 2814

Examiner: L. PHAM

**REQUEST FOR RECONSIDERATION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

December 30, 2005

Sir:

This response is submitted to the Office Action dated July 14, 2005 in the above-identified application.

Claims 45-53 were rejected in the Office Action under 35 U.S.C. §251 as being broadened in a reissue application filed outside the two year statutory period. This rejection is hereby traversed and reconsideration thereof is respectfully requested in view of Applicant's remarks below.

The basis for the rejection as set forth on page 2 of the outstanding Office Action is that the present process claims 45-53 broaden the invention because the present process claims 45-53 have the word "comprising" in their preamble, this word allegedly allowing an additional step of further turning the circular contour portion into a square contour portion resulting in an invention that has a square contour portion and if practiced would allegedly not have